

RTI BURN-IN AND TEST SOCKETS



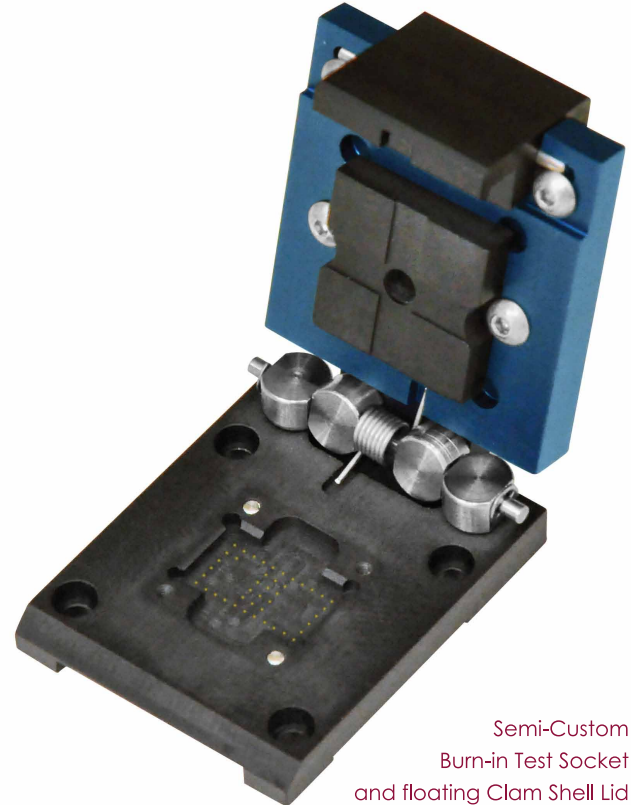
PRODUCT DATA SHEET

PRODUCT OVERVIEW:

Available for QFP, BGA, QFN, LGA and most other package types from 1.0mm to 35mm and from 0.3mm to over 1.27mm pitches. RTI compression mount burn-in and test sockets are a high performance, low cost, semi-custom machined alternative to injection molded burn-in sockets. These reliable test sockets use a clam-shell lid design with a floating z-axis pressure plate allowing for tolerances in package thickness. The sockets use new high performance and innovative flat pin technology for 0.4mm, 0.5mm and larger pitch devices. Multiple types of pins are available for the sockets depending on test requirements. The highest performance pin provides a bandwidth of up to 30GHz @ -1db with a current capacity of 3.0A. Lower cost pins are available for DC burn-in applications. The pins have a high spring force suitable for lead-free packages.

SOCKET FEATURES:

- ◆ Temperatures from -55°C to +155°C
- ◆ Bandwidth up to 30GHz @ -1db loss
- ◆ Contact force: 1.402 (40g) +/- 20%
- ◆ Contact resistance <100 milliohm
- ◆ Max current: 3A
- ◆ Lifespan > 25,000 insertions
- ◆ High performance plastics and aluminum
- ◆ 0.4mm to over 1.27mm pitch
- ◆ Most all package types supported including die level
- ◆ Clam-Shell hinged lid with z-axis pressure plate
- ◆ No additional tooling Fees
- ◆ Small footprint: 1.1in x 1.4in x 0.47in (excluding latch)
- ◆ Fast standard turnaround, expedites available



Semi-Custom
Burn-in Test Socket
and floating Clam Shell Lid



Closed socket
has tight vertical
clearance on a small footprint